

# 低損傷電漿清洗機

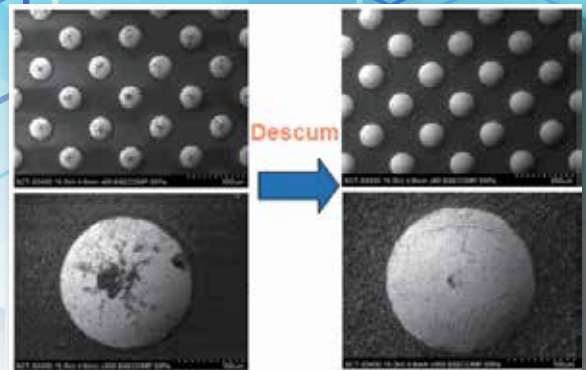
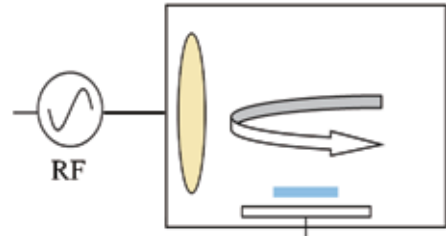
**C SUN**

Remote Plasma Treatment System

**PRSS-BI10R**



## Remote Plasma Source



## 機台特點 Characteristics

- 腔體內專利旋轉機構可提高清潔均勻性  
Patented rotary stage can enhance cleaning uniformity.
- 專利之電漿源(ICP)及腔體設計可有效的防止靜電荷累積  
Patented ICP mode and chamber design can prevent static charge accumulation effectively.
- 無物理轟擊傷害基材及晶片，不影響表面結構與電性  
No physical bombardment to damage substrate and chip. No change on surface structure and electrical property.
- 腔體內具可拆卸、調整的層架，以對應各種尺寸的卡匣、Tray 盤和 Wafer  
Equipped with removable and adjustable cassette to adapt to various sizes of magazines, trays and wafers.
- 高密度電漿配合高效率真空系統設計，節省時間提高製程產能  
High density plasma with high efficiency vacuum system design to gain higher throughput.
- 真空腔體內無電極設計不產生二次金屬污染  
No electrode in the chamber. No secondary contamination.



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**Leading in Thermal and UV Light Processing Equipment**

## PRSS-BI10R 低損傷電漿清洗機

設備電力規格 Power	220V 3φ 50/60 Hz 14kVA
腔體材質 Material of chamber	Aluminum alloy
腔體內部尺寸 Interior chamber ( mm )	W 474mm x D 440mm x H 400mm
電漿源 Plasma source	ICP mode
射頻電源電力規格 Generator power	13.56 MHz, 1kW
製程氣體 Process gas	O <sub>2</sub> 、Ar (Max. 4 gas lines)
氣體流量控制 Gas flow control	MFC ( ±1% of set point ) 註：流量設定 ≥ 全流量40%，控制精度為 ±1% of set point，<40%時控制精度為 ±0.4% of full scale Note: Control accuracy ±1% of set point when flow rate ≥40%, control accuracy ±0.4% of full scale when flow rate <40%
泵浦規格 Standard pump	Dry pump, pumping speed >90 cfm @60 Hz
製程壓力計 Pressure gauge	Capacitive pressure sensor
製程壓力控制 EQ pressure	50~800 mTorr
控制系統 Control system	19.5 inch TFT panel / PC / Windows 10
設備尺寸 Dimension	W1450mm x D1200mm x H2100mm
規範 Compliance	SEMI S2-01, SEMI S8-01, SECS/GEM

Due to C SUN continuing efforts to improve their systems, these specifications are subject to change without notice.  
受長期研發需要，本公司保有規格修改之權利，恕不另行通知

DM2023Q2-000-TW

## 應用 Applications

**Wire Bonding前表面清潔**  
Surface cleaning before wire bonding

**LED封裝前表面活化和清潔**  
Surface activation and cleaning before LED packaging

**集成電路鍵合前表面清潔**  
Surface cleaning before IC bonding

**Solar cell表面粗化及去邊蝕刻**  
Solar cell surface roughening and edge etching

**光阻、殘膠去除**  
PR stripping、descum

**觸控模組膠合前的表面活化和清潔**  
Surface activation and cleaning before TP module lamination

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